

6-Layer Rigid-Flex A1

Top L1	solder mask		Coverlay 25/20		15 µm	Lacquer
	outer copper				35 µm	Copper
IL2	polyimid				50 µm	Polyimid
	inner copper				18 µm	Copper
IL3	low flow				60 µm	Prepreg
	inner copper				18 µm	Copper
IL4	core				564 µm	FR4
	outer copper				35 µm	Copper
IL5	low flow				60 µm	Prepreg
	inner copper				18 µm	Copper
Bottom L6	core				564 µm	FR4
	outer copper				35 µm	Copper
	solder mask				15 µm	Lacquer
Total finished thickness:					1,49 mm	
Tolerance ±					10%	
Maximum thickness					1,6357 mm	
Minimum thickness					1,3383 mm	

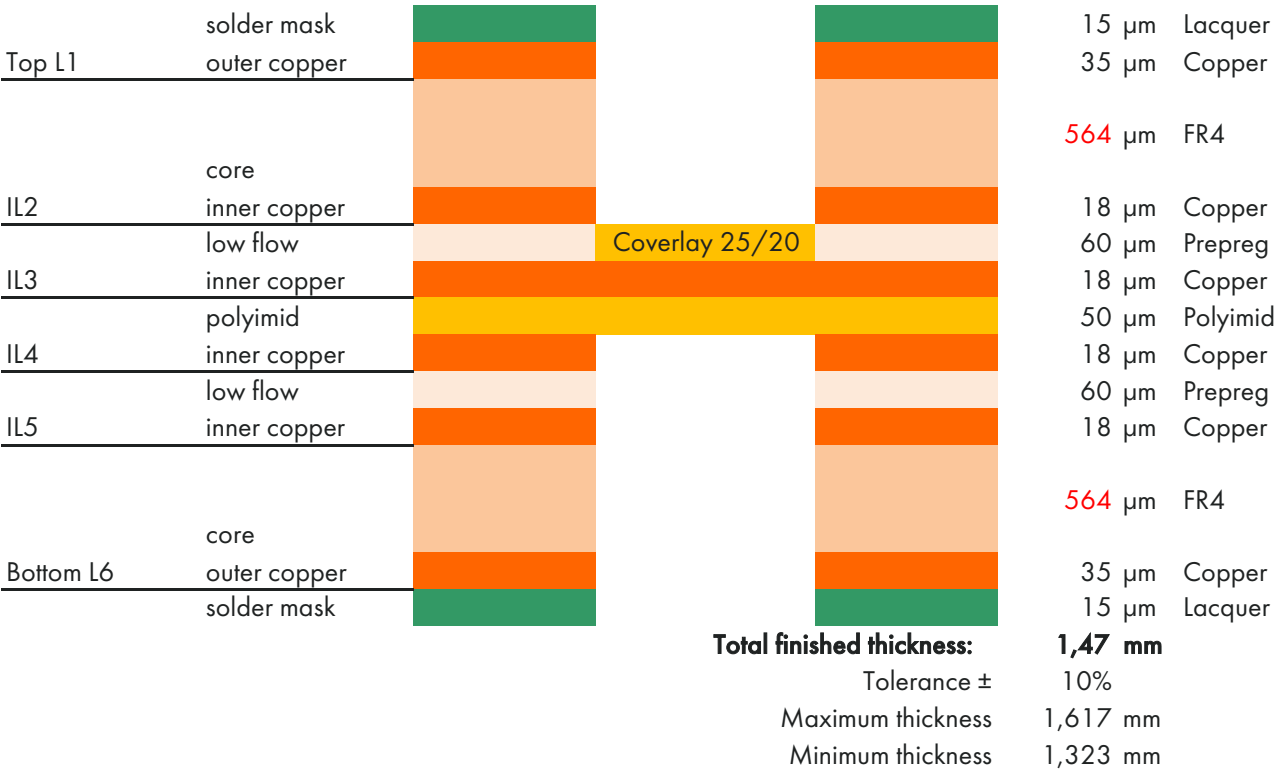
FR4 core thickness 1,0 mm	364 µm	FR4
FR4 core thickness 1,5 mm	564 µm	FR4
FR4 core thickness 2,0 mm	964 µm	FR4

6-Layer Rigid-Flex A2

Top L1	solder mask		Coverlay 25/20		15 µm	Lacquer
	outer copper				35 µm	Copper
IL2	polyimid				50 µm	Polyimid
	inner copper				18 µm	Copper
IL3	low flow		Coverlay 25/20		60 µm	Prepreg
	inner copper				18 µm	Copper
IL4	core				564 µm	FR4
	outer copper				35 µm	Copper
IL5	low flow				60 µm	Prepreg
	inner copper				18 µm	Copper
Bottom L6	core				564 µm	FR4
	outer copper				35 µm	Copper
	solder mask				15 µm	Lacquer
Total finished thickness:					1,49 mm	
Tolerance ±					10%	
Maximum thickness					1,6357 mm	
Minimum thickness					1,3383 mm	

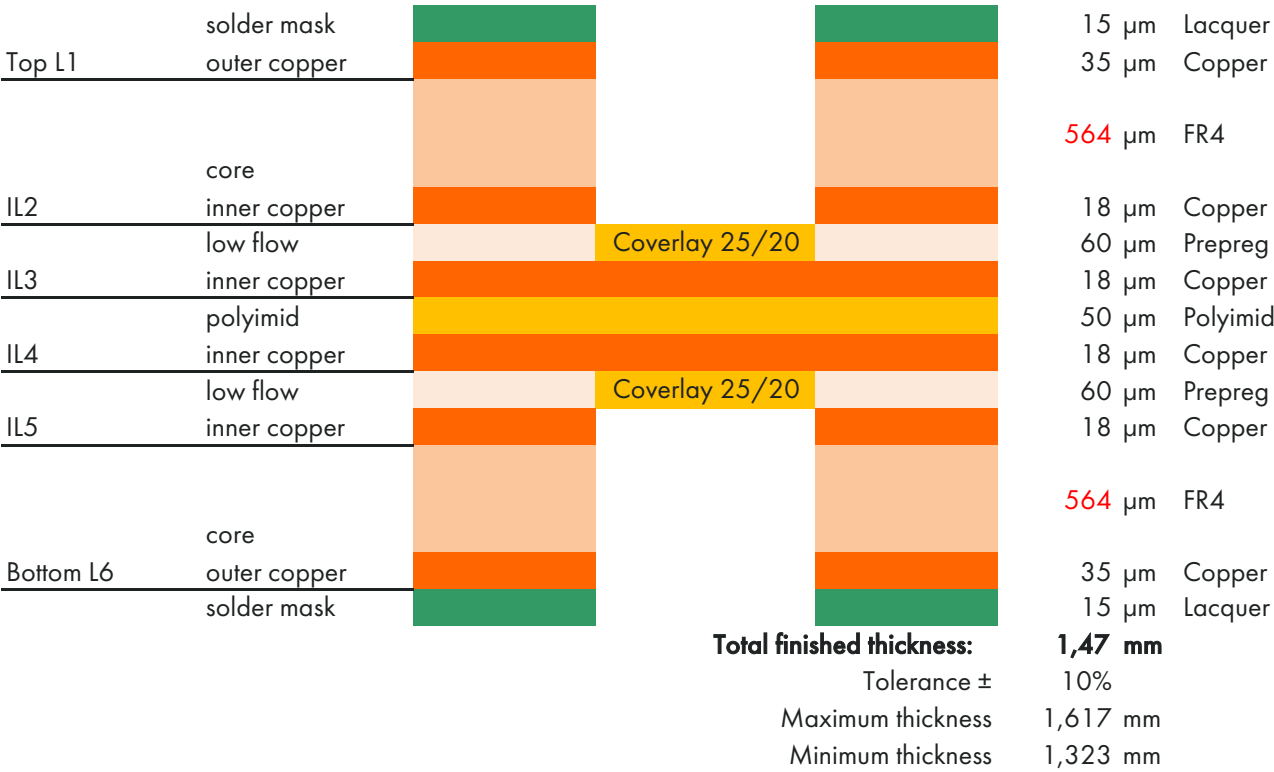
FR4 core thickness 1,0 mm	364 µm	FR4
FR4 core thickness 1,5 mm	564 µm	FR4
FR4 core thickness 2,0 mm	964 µm	FR4

6-Layer Rigid-Flex I1



FR4 core thickness 1,0 mm 364 µm FR4
FR4 core thickness 1,5 mm 564 µm FR4
FR4 core thickness 2,0 mm 964 µm FR4

6-Layer Rigid-Flex I2



FR4 core thickness 1,0 mm 364 µm FR4
FR4 core thickness 1,5 mm 564 µm FR4
FR4 core thickness 2,0 mm 964 µm FR4